

REV.	ECN NO.	DESCRIPTION	DATE	DESIGN
06	--	Add description of package quantity	2021.07.20	Dorian
07	--	Chamfer changed to fillet	2021.08.02	Dorian

NOTES:

- ELECTRICAL CHARACTERISTICS:
 - 1-1 CURRENT RATING: 1.1 A PER PIN, 30°C RISE ABOVE AMBIENT.
 - 1-2 CONTACT RESISTANCE: 30 MILLIOHMS MAX. INITIAL, 50 MILLIOHMS MAX. AFTER TEST.
 - 1-3 INSULATION RESISTANCE: 1000 MEGOHMS MIN..
 - 1-4 DIELECTRICAL WITHSTAND VOLTAGE: 500 V AC MIN. AT SEA LEVEL.
- MECHANICAL CHARACTERISTICS:
 - 2-1 CONTACT INSERTION FORCE: 1.15 N MAX. PER CONTACT PAIR.
 - 2-2 CONTACT REMOVAL FORCE: 0.15 N MIN. PER CONTACT PAIR.
 - 2-3 DURABILITY: 50 MATING AND UNMATING CYCLES.
 - 2-4 CONTACT RETENTION FORCE: 3.43 N MIN.
- ENVIRONMENTAL CHARACTERISTICS:
 - 3-1 OPERATING TEMPERATURE RANGE: -40°C TO +105°C .
- RECOMMENDED PROCESS: IR REFLOW 260°C, 10 s
- RECOMMENDED STEEL BOARD THICKNESS: 0.15MM.
- HF COMPLIANT.

PART P/N:
121P-C6T * -K1 * T
COLOR
W=WHITE
B=BLACK
CONTACT AREA GOLD PLATING:
G= GOLD FLASH
B= 15u" GOLD
C= 30u" GOLD

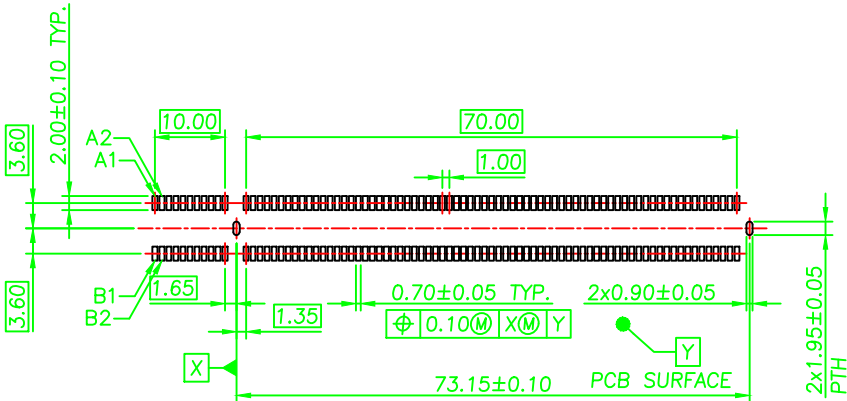
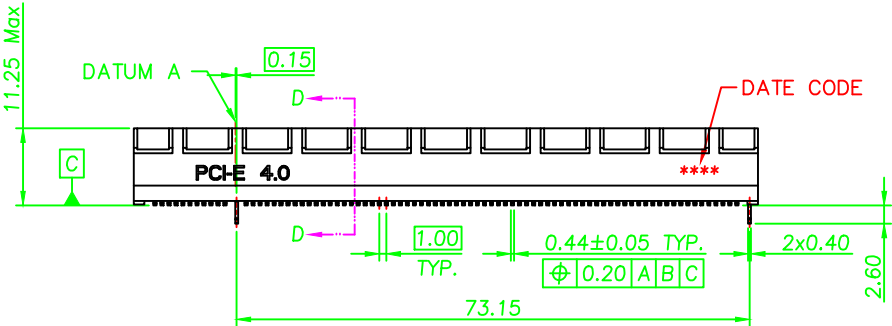
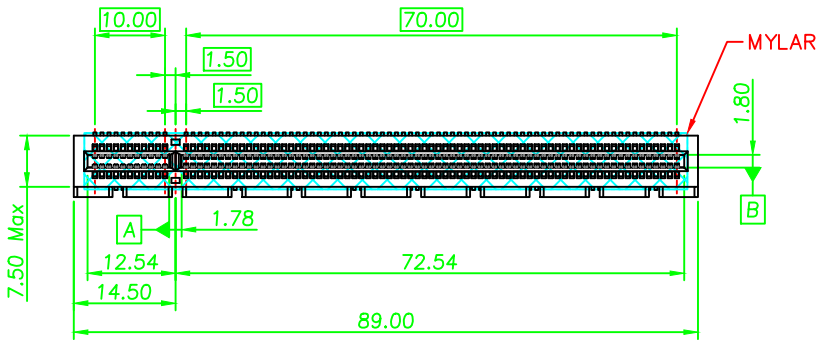
SECTION D-D

3	CONTACT	COPPER ALLOY	50u" NICKEL PLATING OVERALL UNDERPLATED. 100u" MATTE TIN PLATING OVER NICKEL AT TAIL. GOLD PLATING ON CONTACT AREA.
2	HOOK	COPPER ALLOY	50u" NICKEL PLATING OVERALL UNDERPLATED. 100u" MATTE TIN PLATING OVER NICKEL AT TAIL.
1	HOUSING	THERMOPLASTIC UL 94V-0	MOLDED WHITE OR BLACK
ITEM	DESCRIPTION	MATERIAL	TREATMENT
DIM	TOL	DIM	DEG
X	±0.50	X°	±8°
X.X	±0.35	X.X°	±5°
X.XX	±0.25	X.XX°	±3°
X.XXX	±0.15	X.XXX°	±2°
DESIGN:	CHARLES	2021.03.10	FILE:
CHECK:			DRAW NO.
APPROVED			P/N: 121P-C6T*-K1*T
			UNIT: mm SCALE: 1:1
			REV: 07 SHEET: 1/3
			MODEL:

JOINSOO建舜電子

DRAW NAME:
PCIE-X16 Gen4
164P SMT TYPE CONN

C-DWG



RECOMMENDED PCB LAYOUT

